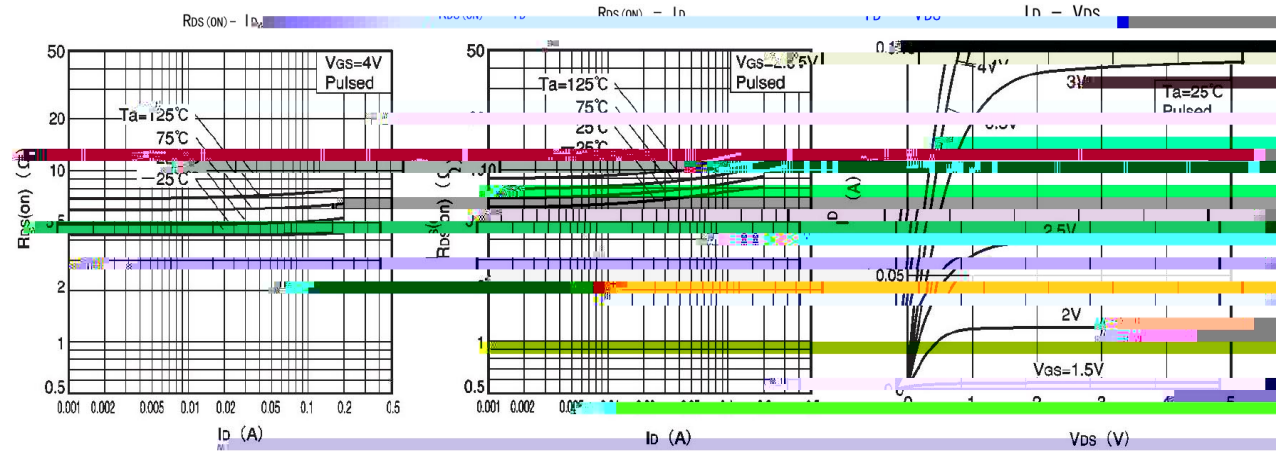
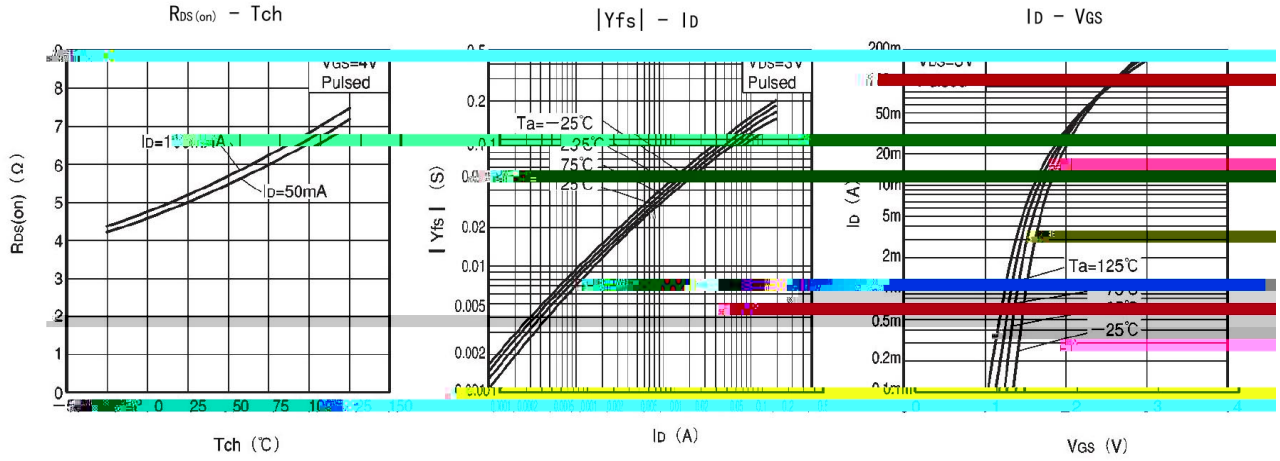
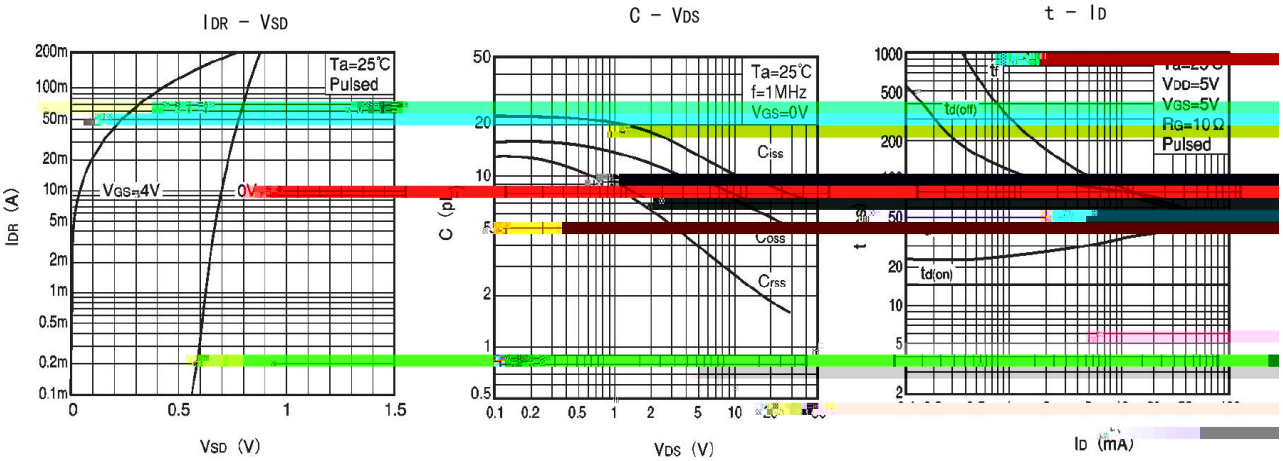
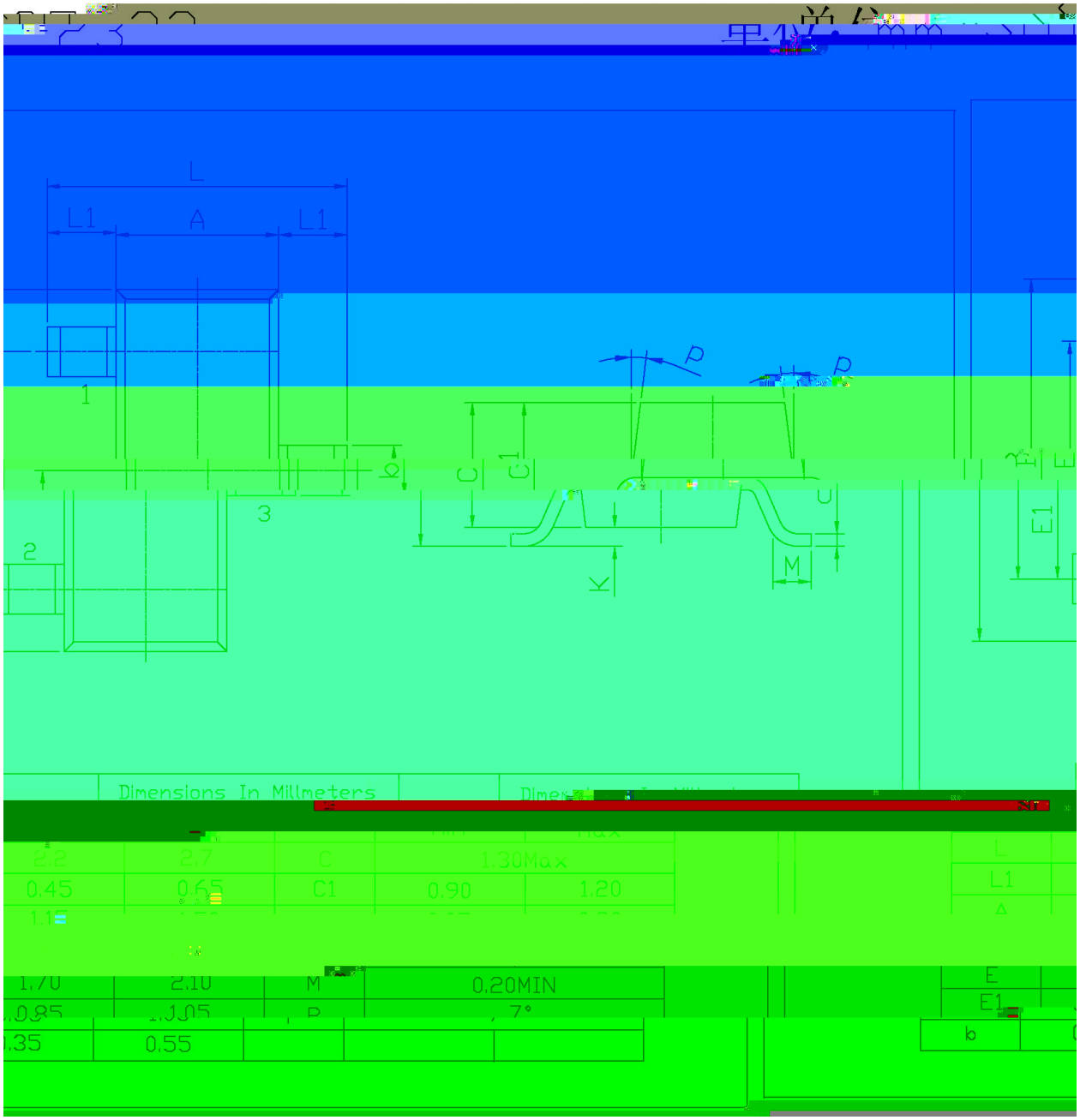
/ Electrical Characteristic Curve



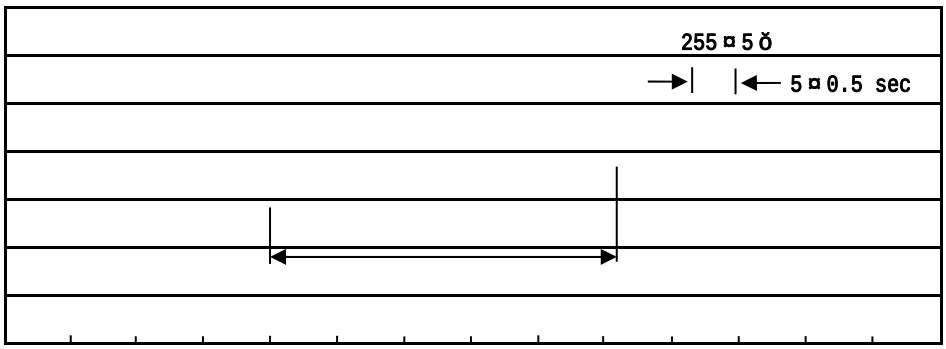




/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب χ

1 أ 150 200 ڑ 60 120sec;

2 255±5 ڑ ٨ 5±0.5sec;

3 ٧ ه 2 10 /sec.

Note:

1.Preheating:150~200 , Time:60~120sec.

2.Peak Temp.:255±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

χ 260±5 ڑ χ 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

` ᒪ / REEL

Package Type	Units					Dimension		(unit mm^3)

/ Notices